

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) An optoelectronic component based on a surface mount technology, said optoelectronic component comprising:

an electrically conductive frame to form a base for an assembly;

at least one optoelectronic chip mounted on said base;

an electrical connection between said optoelectronic chip and said electrically conductive frame by wiring means;

soldering terminals provided by the base are part of said electrically conductive frame and are exposed only at bottom and side portions of said component; and

a series of grooves and wings crafted in said electrically conductive frame to enhance anchorage and minimize an occurrence of de-lamination,

wherein said electrically conductive frame is entirely encapsulated with a transparent or translucent material to enable optical radiation to be transmitted or received via said optoelectronic component, and

wherein said soldering terminals do not extend beyond an outline of said encapsulation material.

2-9. (Canceled)

10. (Previously presented) The optoelectronic component as claimed in claim 1, wherein said electrically conductive frame is made of a metal.

11. (Previously presented) The optoelectronic component as claimed in claim 1, wherein a lens structure is incorporated as part of said encapsulation material.

12. (Previously presented) The optoelectronic component as claimed in claim 1, wherein a multiple lens structure is incorporated as part of said encapsulation material.

13. (Previously presented) The optoelectronic component as claimed in claim 1, wherein a cavity is formed within said electrically conductive frame and is used to attach said optoelectronic chip within said cavity and serve as a reflector.

14. (Canceled)